## **OVSARGB4R8**



#### Features:

- Surface mount device packaged in 8mm tape on 7" diameter reel
- Compatible with automatic placement equipment
- Compatible with infrared and vapor phase reflow solder
- Dimensions: 3.5 x 2.8 x 1.9 mm
- 120°viewing angle



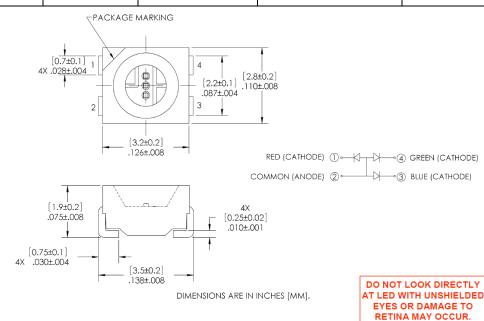
### **Description:**

The OVSARGB4R8 provides full color light output from a single package, 3-die design. This surface mount package is an efficient solution in modular applications that require uniform brightness and color-on-demand. Light output is optimized by an interior reflector and the wide viewing angle adds flexibility for applications ranging from hand-held appliances to automotive interiors.

### **Applications:**

- RGB full-color indoor and outdoor displays
- Backlighting
- · Coupling into light guides
- Automotive interiors
- Entertainment equipment

Part Number		Lens Color			
	Туре	Material	Emitted Color	Intensity Typ. Mcd	
OVSARGB4R8	R	AllnGaP	Red	635	Diffused
	G B	InGaN InGaN	Green Blue	1000 335	



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General Note

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ATTENTION

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# **OVSARGB4R8**



# **Electrical Specifications**

Absolute Maximum Ratings T<sub>A</sub> = 25° C unless otherwise noted

		RATING			
PARAMETER	R	G	В	UNIT	
Storage Temperature		-40 ~ +100			
Operating Temperature		-40 ~ +100	°C		
Reverse Voltage		5	V		
Continuous Forward Current (1 chip on)	50	25	25	mA	
Peak Forward Current (10% Duty Cycle, PW ≤ 100 μsec, 1 chip on)	200	100	100	mA	
Power Dissipation	130	100	100	mW	
Junction Temperature	110	110	110	°C	
Junction/ ambient (1 chip on)	450	400	450	°C/W	
Junction/ ambient (3 chip on)	650	580	680	°C/W	
Junction/ solder point (1 chip on)	300	280	300	°C/W	
Junction/ solder point (3 chip on)	450	430	480	°C/W	
Electrostatic Discharge Classification (JEDEC-JESD22-A114F)	Class 1C				
Moisture Sensitivity Level (IPC/JEDEC J-STD-020C)				5a / 24 Hrs	

### **Electrical Characteristics** T<sub>A</sub> = 25° C unless otherwise noted

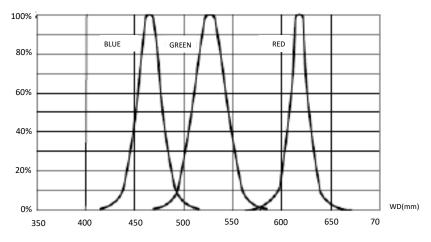
CYMAROL	DADAMETED	VALUES				LINUT	CONDITIONS
SYMBOL	PARAMETER		R	G	В	UNIT	CONDITIONS
I <sub>V</sub>	Luminaus Intansitu	Min	450	710	224	mad	1 - 20 m A
	Luminous Intensity		635	1000	335	mcd	I <sub>F</sub> = 20 mA
$V_{F}$	Forward Voltago	Тур	2.0	3.2	3.2	V	I <sub>F</sub> = 20 mA
	Forward Voltage	Max	2.6	4.0	4.0		
I <sub>R</sub>	Reverse Current		10	10	10	μΑ	V <sub>R</sub> = 5 V
$\lambda_{D}$	Dominant Wavelength		619-624	520-540	460-475	nm	I <sub>F</sub> = 20 mA
2 0½	50% Power Angle	·	120	120	120	deg	I <sub>F</sub> = 20 mA
Δλ	Spectral Radiation Bandwidth		24	38	28	nm	I <sub>F</sub> = 20 mA

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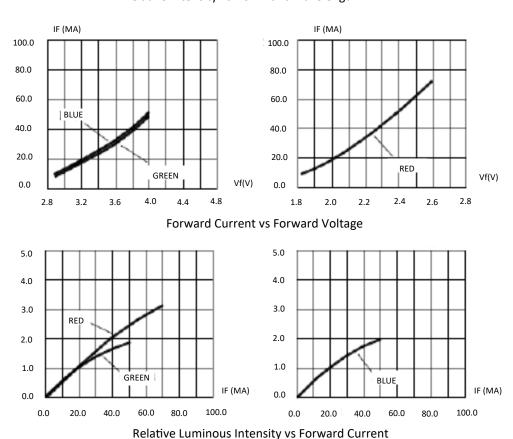
# **OVSARGB4R8**



### **Typical Electro-Optical Characteristics Curves**



Relative Intensity vs Dominant Wavelength



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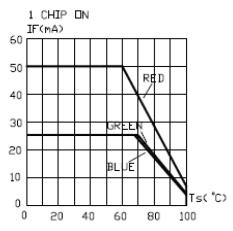
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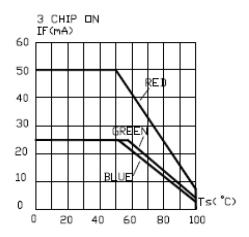
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## **OVSARGB4R8**

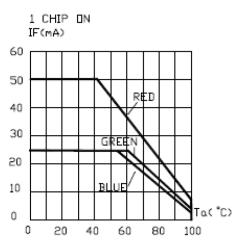


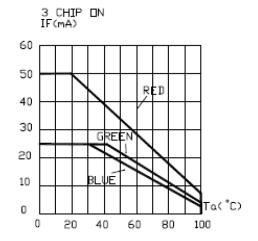
### **Typical Electro-Optical Characteristics Curves**



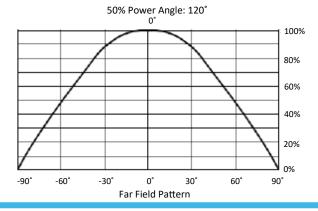


#### Maximum Forward DC Current vs Solder Point Temperature





#### Maximum Forward DC Current vs Ambient Temperature



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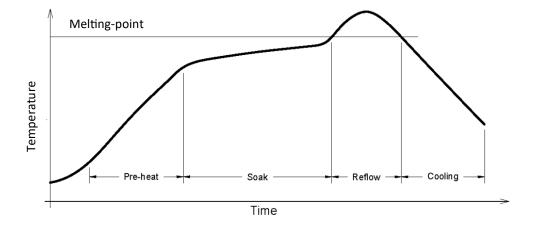
## **OVSARGB4R8**



### **Reflow Solder Profile**

#### Manual soldering by soldering iron

- The use of a soldering iron of less than 25W is recommended. The temperature of the iron must be kept at below 315C with soldering time within 2 seconds
- The epoxy resin of the SMD LED should not contact the tip of the soldering iron
- No mechanical stress should be exerted on the resin portion of the SMD LED during soldering.
- Handling of the SMD LED should be done when the package has been cooled down to below 40°C or less. This is to prevent LED failures due to thermal-mechanical stress during handling.
- The temperature (top surface of the SMD LED) profile is as below:



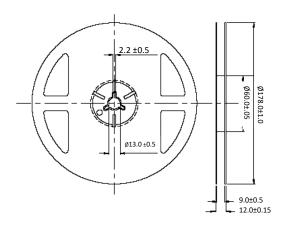
Solder = Lead-Free
Average ramp-up rate = 4°C / sec. max
Preheat temperature: 150 - 200°C
Preheat time: 120 sec. max.
Ramp-down rate = 6°C / sec. max.
Peak temperature = 250°C max.
Time within 5°C of actual peak temperature = 10 sec. max
Duration above 217°C is 60 sec. max

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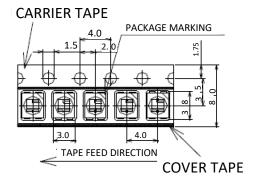
# **OVSARGB4R8**



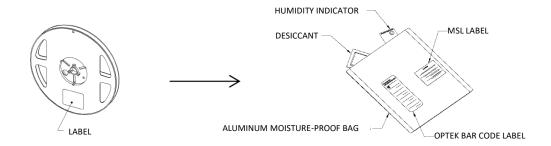
#### **Reel Dimensions: 7-inch reel**



### Carrier Tape Dimensions: Loaded quantity 2,000 pieces per reel



### **Moisture Resistant Packaging**



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